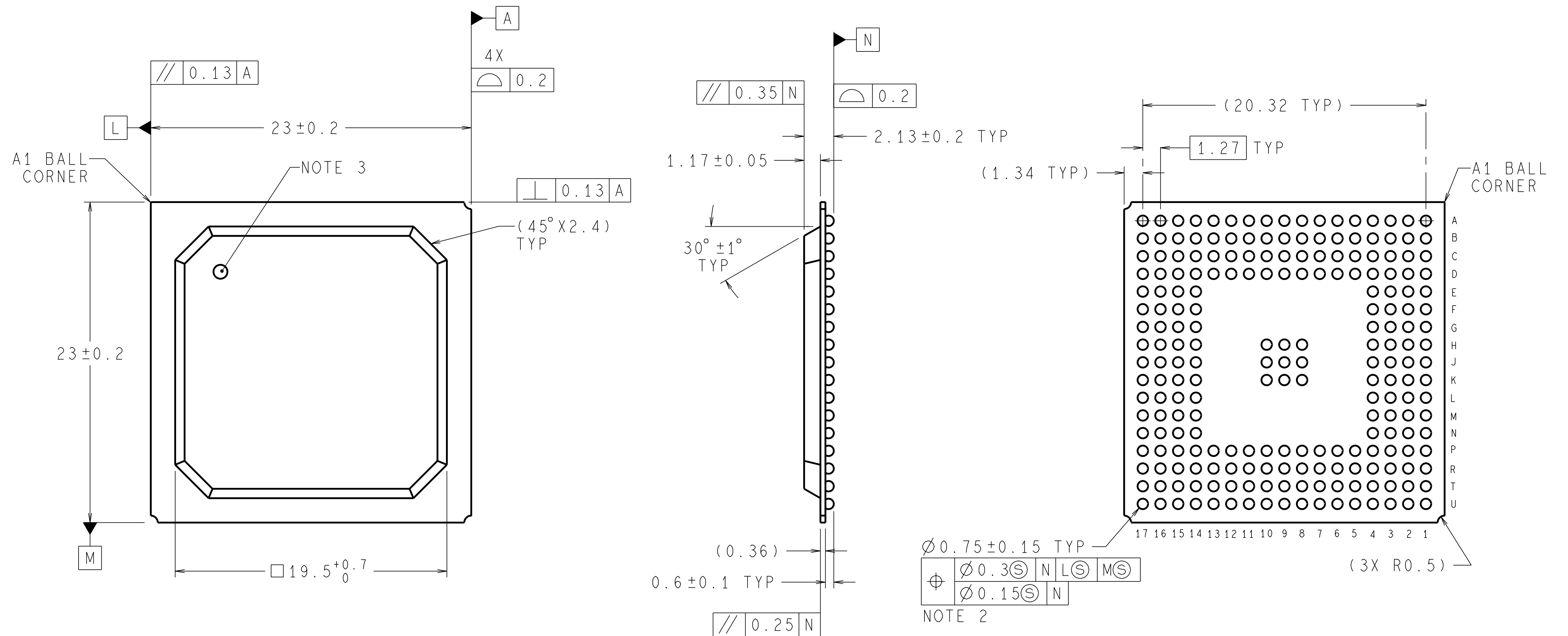
REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12221	06/02/1999	MS/MJL
B	REVISE GEOM TOL'S; BALL DIM Ø0.75±0.15 WAS 0.76+0.14/-0.16; DIM 2.13±0.2 WAS 2.32 MAX; REVISE NOTE 4.	217	12/04/2000	MS/AP



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION.
4. REFERENCE JEDEC REGISTRATION MO-151, VARIATION BAJ-2.

APPROVALS	DATE
DRAWN MARTA SUCHY	06/02/1999
DFTG. CHK. THANH LEQUANG	12/05/2000
ENGR. CHK. ANINDYA PODDAR	12/05/2000

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

PBGA, 23 X 23 X 2.13mm, 217 BALL, 1.27mm PITCH

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]	N/A	C	(SC)MKT-UDD217A	B

DO NOT SCALE DRAWING

SHEET 1 of 1